#### Fall-2020 UM-SJTU JI Ve311 Lab #3

Instructor: Dr. Chang-Ching Tu

Due: 11:59 am, December 4, 2020 (Friday)

Note:

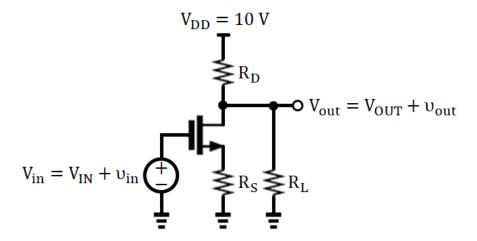
(1) Please use A4 size papers.

(2) The lab report should be submitted online individually.

(3) Use Proteus 8.10 for simulation before the lab session. In the Proteus library, you should be able to find all the components used in the schematics.

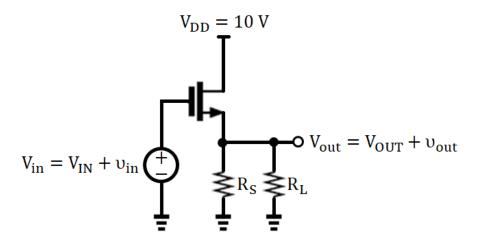
The lab report must include both the simulation and measurement results.

- 1. [Common-Source with Source Degradation Amplifier]
  - (a) [20%] ( $R_L = \infty$ ) Design and build a common-source with source degradation amplifier, which has a voltage gain  $A_{\upsilon} > 5$ , using NMOS (**VN0104**). Plot  $V_{OUT}$  vs  $V_{IN}$ . Is the voltage gain  $A_{\upsilon}$  close to  $R_D/R_S$ ? (Hint: First choose appropriate  $R_D$  and  $R_S$ . Second, perform DC sweep to find out a  $V_{IN}$  at which the magnitude of slope is more than 5. At the same time, make sure the NMOS is in the saturation region. If not, change for another  $R_D$  and  $R_S$ , and repeat the DC sweep again.)
  - (b) [15%] (  $R_L = \infty$  ) For  $V_{in} = V_{IN} + 0.01 sin(2\pi 10^2 \cdot time)$ , plot  $V_{out} = V_{OUT} + \upsilon_{out}$  vs time. Confirm that the amplitude of  $\upsilon_{out}$  is equal to  $0.01 \times A_{\upsilon}$ .
  - (c) [15%] ( $R_L = 50 \text{ k}\Omega$ ) For  $V_{in} = V_{IN} + 0.01 \text{sin}(2\pi 10^2 \cdot \text{time})$ , plot  $V_{out} = V_{OUT} + \upsilon_{out}$  vs time. Does the amplitude of  $\upsilon_{out}$  become smaller than  $0.01 \times A_\upsilon$ ? If so, explain the reasons. (Note: Make sure the NMOS remains in the saturation region.)



#### 2. [Source Follower]

- (a) [20%] ( $R_L = \infty$ ) Design and build a source follower, which has a voltage gain  $A_v > 0.5$ , using NMOS (**VN0104**). Plot  $V_{OUT}$  vs  $V_{IN}$ . Is the voltage gain  $A_v$  close to unity? (Hint: First choose appropriate  $R_S$ . Second, perform DC sweep to find out a  $V_{IN}$  at which the magnitude of slope is more than 0.5. Here the NMOS is always in the saturation region.)
- (b) [15%] (  $R_L = \infty$  ) For  $V_{in} = V_{IN} + 0.05 sin(2\pi 10^2 \cdot time)$ , plot  $V_{out} = V_{OUT} + \upsilon_{out}$  vs time. Confirm that the amplitude of  $\upsilon_{out}$  is equal to  $0.05 \times A_\upsilon$ .
- (c) [15%] ( $R_L = 50 \text{ k}\Omega$ ) For  $V_{in} = V_{IN} + 0.05 \text{sin}(2\pi 10^2 \cdot \text{time})$ , plot  $V_{out} = V_{OUT} + \upsilon_{out}$  vs time. Does the amplitude of  $\upsilon_{out}$  still maintain around  $0.05 \times A_{\upsilon}$ ? If so, explain the reasons.





# N-Channel Enhancement-Mode Vertical DMOS FET

#### **Features**

- Free from secondary breakdown
- ► Low power drive requirement
- Ease of paralleling
- ► Low C<sub>ISS</sub> and fast switching speeds
- Excellent thermal stability
- ► Integral source-drain diode
- High input impedance and high gain

#### **Applications**

- Motor controls
- Converters
- Amplifiers
- Switches
- Power supply circuits
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

#### **General Description**

This enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven, silicongate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

### **Ordering Information**

Device	Package Option	Wafer / Die Options					
	TO-92	NW (Die in wafer form)	NJ (Die on adhesive tape)	ND (Die in waffle pack)			
VN0104	VN0104N3-G	VN1504NW	VN1504NJ	VN1504ND			

For packaged products, -G indicates package is RoHS compliant ('Green'). Devices in Wafer / Die form are RoHS compliant ('Green'). Refer to Die Specification VF15 for layout and dimensions.

## **Product Summary**

BV <sub>DSS</sub> /BV <sub>DGS</sub> (V)	$R_{DS(ON)} \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ $	l <sub>D(ON)</sub> (min) (A)				
40	3.0	2.0				

## **Absolute Maximum Ratings**

Parameter	Value
Drain-to-source voltage	BV <sub>DSS</sub>
Drain-to-gate voltage	BV <sub>DGS</sub>
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

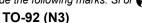
### **Pin Configuration**



### **Product Marking**

SiVN 0 1 0 4 YYWW = Year Sealed WW = Week Sealed YYWW = "Green" Packaging

Package may or may not include the following marks: Si or 🌎



#### **Thermal Characteristics**

Package	I <sub>D</sub> (continuous) <sup>†</sup> (mA)	I <sub>D</sub> (pulsed) (A)	Power Dissipation @T <sub>c</sub> = 25°C (W)	θ <sub>jc</sub> (°C/W)	θ <sub>ja</sub> (°C/W)	l <sub>DR</sub> † (mA)	I <sub>DRM</sub> (A)
TO-92	350	2.0	1.0	125	170	350	2.0

#### Notes:

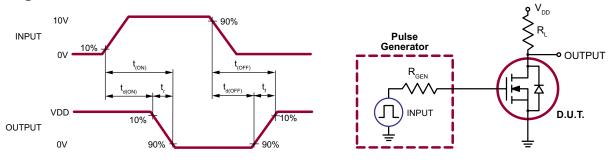
#### Electrical Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Sym	Parameter	Min	Тур	Max	Units	Conditions	
BV <sub>DSS</sub>	Drain-to-source breakdown voltage	40	-	-	V	$V_{GS} = 0V, I_{D} = 1.0 \text{mA}$	
$V_{GS(th)}$	Gate threshold voltage	0.8	-	2.4	V	$V_{GS} = V_{DS}$ , $I_D = 1.0 \text{mA}$	
$\Delta V_{GS(th)}$	Change in V <sub>GS(th)</sub> with temperature	-	-3.8	-5.5	mV/°C	$V_{GS} = V_{DS}$ , $I_D = 1.0 \text{mA}$	
I <sub>GSS</sub>	Gate body leakage	-	-	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
		-	-	1.0		$V_{GS} = 0V, V_{DS} = Max Rating$	
I <sub>DSS</sub>	Zero gate voltage drain current		-	100	μA	$V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$ , $T_{A} = 125$ °C	
ı	On-state drain current	0.5	1.0	-	Α	$V_{GS} = 5.0V, V_{DS} = 25V$	
I <sub>D(ON)</sub>	On-state drain current	2.0	2.5	-		$V_{GS} = 10V, V_{DS} = 25V$	
D	Static drain-to-source on-state resistance	-	3.0	5.0	Ω	$V_{GS} = 5.0V, I_{D} = 250mA$	
R <sub>DS(ON)</sub>		-	2.5	3.0		$V_{GS} = 10V, I_{D} = 1.0A$	
$\Delta R_{DS(ON)}$	Change in R <sub>DS(ON)</sub> with temperature	-	0.70	1.0	%/°C	$V_{GS} = 10V, I_{D} = 1.0A$	
G <sub>FS</sub>	Forward transductance	300	450	-	mmho	$V_{DS} = 25V, I_{D} = 500mA$	
C <sub>ISS</sub>	Input capacitance	-	55	65		V <sub>GS</sub> = 0V,	
C <sub>oss</sub>	Common source output capacitance	-	20	25	pF	$V_{DS} = 25V$ ,	
C <sub>RSS</sub>	Reverse transfer capacitance	-	5.0	8.0		f = 1.0MHz	
t <sub>d(ON)</sub>	Turn-on delay time	-	3.0	5.0		$V_{DD} = 25V,$ $I_{D} = 1.0A,$	
t <sub>r</sub>	Rise time	-	5.0	8.0	ns		
t <sub>d(OFF)</sub>	Turn-off delay time	-	6.0	9.0		$R_{GEN} = 25\Omega$	
t <sub>f</sub>	Fall time	-	5.0	8.0		OLIV	
$V_{\scriptscriptstyle{SD}}$	Diode forward voltage drop	-	1.2	1.8	V	$V_{GS} = 0V, I_{SD} = 1.0A$	
t <sub>rr</sub>	Reverse recovery time	-	400	-	ns	$V_{GS} = 0V, I_{SD} = 1.0A$	

#### Notes:

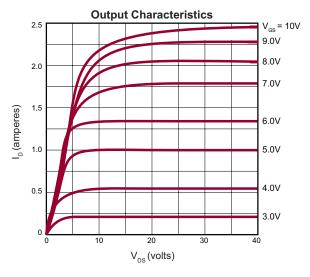
- All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
   All A.C. parameters sample tested.

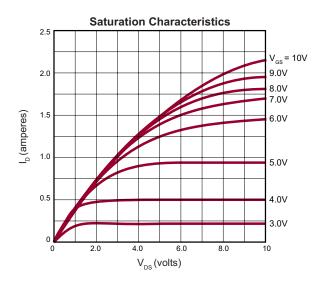
## **Switching Waveforms and Test Circuit**

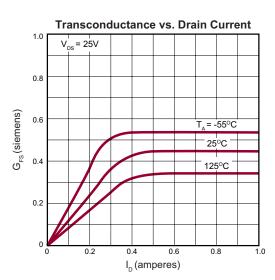


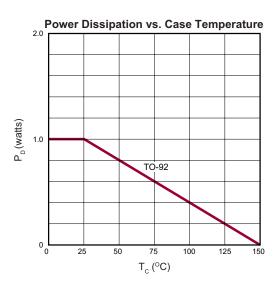
<sup>†</sup>  $I_D$  (continuous) is limited by max rated  $T_i$ .

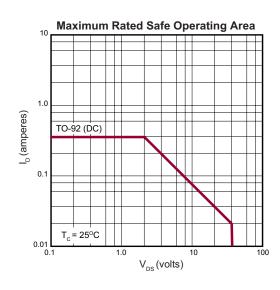
## **Typical Performance Curves**

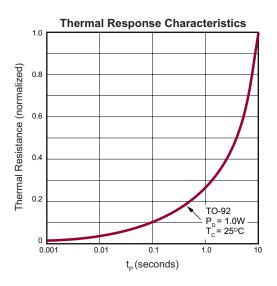




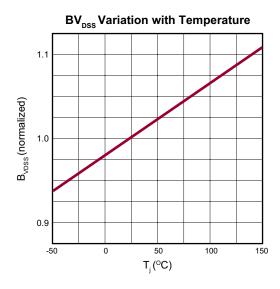


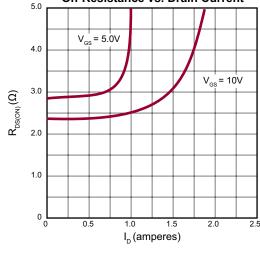




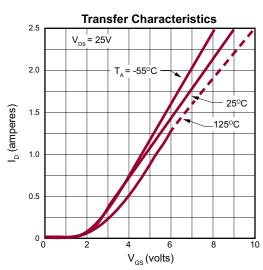


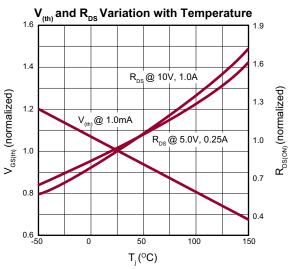
## **Typical Performance Curves** (cont.)

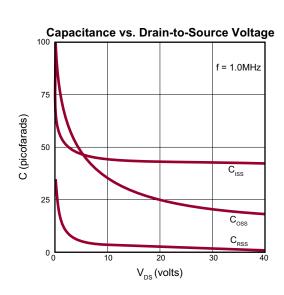


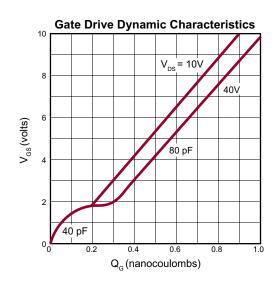


On-Resistance vs. Drain Current

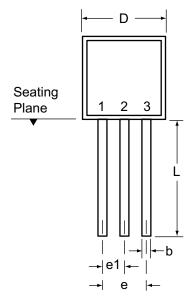


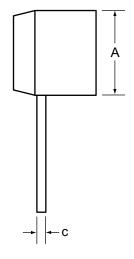






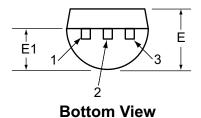
# 3-Lead TO-92 Package Outline (N3)





**Front View** 

Side View



Symbol		Α	b	С	D	E	E1	е	e1	L
Dimensions (inches)	MIN	.170	.014 <sup>†</sup>	.014 <sup>†</sup>	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 <sup>†</sup>	.022 <sup>†</sup>	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version E041009.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="http://www.supertex.com/packaging.html">http://www.supertex.com/packaging.html</a>.)

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<sup>\*</sup> This dimension is not specified in the JEDEC drawing.

<sup>†</sup> This dimension differs from the JEDEC drawing.

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